

Title (en)

PLANARIZATION OF METAL LAYER OVER PHOTORESIST

Title (de)

PLANARISIERUNG EINER METALLSCHICHT ÜBER FOTOIRESIST

Title (fr)

PLANARISATION D UNE COUCHE MÉTALLIQUE SUR UN PHOTORÉSISTANT

Publication

**EP 1938365 A4 20110202 (EN)**

Application

**EP 06814963 A 20060920**

Priority

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- US 23124905 A 20050920

Abstract (en)

[origin: US2007066063A1] The present invention provides a method for planarizing a metal layer, and a method for manufacturing a micro pixel array. The method for planarizing the metal layer, without limitation, may include the steps of forming a metal layer over a photoresist layer, and then planarizing the metal layer using a chemical mechanical planarization process.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

- [X1] US 2004125346 A1 20040701 - HUIBERS ANDREW G [US]
- See references of WO 2007035761A2

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DOCDB simple family (publication)

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